

Notice of References Cited

Application/Control No.

09/383,210

Applicant(s)/Patent Under
Reexamination
HUBER ET AL.

Examiner

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Art Unit

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Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Kunze, The Heatmanagement Company, Thermally Conductive Soft-Silicone Interface Materials, internet site www.heatmanagement.com
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